



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant : N. Sakamoto et al.

Art Unit : 2815

Serial No. : 09/810,101

Examiner : Clark, Shiela V.

Filed : March 16, 2001

Title : RADIATION SUBSTRATE AND SEMICONDUCTOR MODULE

Commissioner for Patents

Washington, D.C. 20231

TECHNOLOGY CENTER 2800

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RESPONSE

In response to the action mailed September 11, 2002, please amend the application as follows:

In the claims:

Please cancel claims 26 to 31 without prejudice.

Please amend claims 1 to 6, 11 to 23, and 25 as follows (unamended claims are shown in bold, small type-face for ease of reference only):

-- 1. (Amended) A heat radiating device comprising:

a heat radiating substrate containing Al as a major component; and

a metal film containing Cu, Ag, Sn, Ni, or Au disposed on the heat radiating substrate.

2. (Amended) A heat radiating device according to claim 1, wherein the metal film

consists of a plating film.

3. (Amended) A heat radiating device according to claim 1, wherein the metal film is configured to contact a metal body provided on a back surface of a semiconductor

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I hereby certify under 37 CFR §1.8(a) that this correspondence is being deposited with the United States Postal Service as first class mail with sufficient postage on the date indicated below and is addressed to the Commissioner for Patents, Washington, D.C. 20231.

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January 3, 2003

Carol Tyrrell

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